

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

# TLGC245P

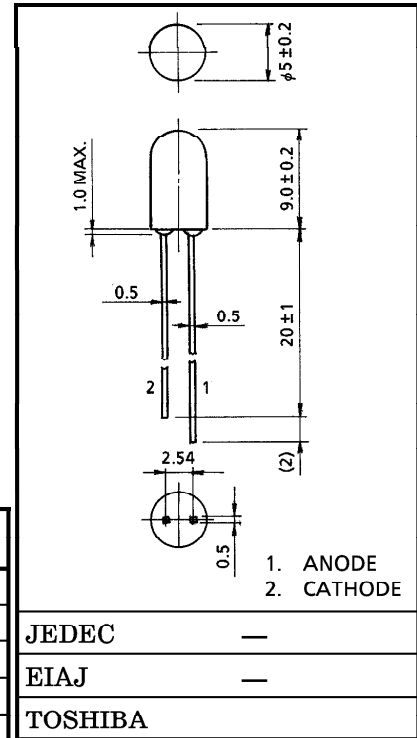
PANEL CIRCUIT INDICATOR

Unit in mm

- 5mm DIAMETER (T1-3/4) FLANGELESS PACKAGE
- All Plastic Mold Type Colorless Clear Lens
- Low Drive Current, High Intensity Green Light Emission.
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Without stand-offs
- Fast Response Time, Capable of Pulse Operation.
- High Power Luminous Intensity Suitable for Outdoor Message Signboard.

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current	I <sub>F</sub>	40	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	120	mW
Operating Temperature Range	T <sub>opr</sub>	-20~85	°C
Storage Temperature Range	T <sub>stg</sub>	-30~100	°C



Weight : 0.31g

ELECTRO-OPTICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA	—	2.15	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4V	—	—	5	μA
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20mA	47.6	150	—	mcd
Peak Emission Wave Length	λ <sub>p</sub>	I <sub>F</sub> = 20mA	—	567	—	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20mA	—	25	—	nm

**PRECAUTION**

Please be careful of the followings

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.  
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

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